



Design of a 19-22GHz Wideband LNA in 0.13 μ m CMOS Technology using Transmission Lines

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OUTLINE



- ❖ Motivation & Objectives
- ❖ Introduction & Applications of LNA
- ❖ Low Noise Amplifier (LNA) Specifications
- ❖ Common Wideband LNA Topologies
- ❖ Resistive Feedback Topology
- ❖ Design Methodology
- ❖ Schematic Design
- ❖ Layout Design & Post-Layout Simulation Results
- ❖ Comparison with State-of-the-art +15GHz LNAs
- ❖ Conclusion & Future Prospects

MOTIVATION



- ❑ Obtain performance comparisons among various wideband topologies
- ❑ Learn new approaches to the challenges of small-area fully integrated design
- ❑ Understand the design considerations of RF front-ends, particularly RF receivers & LNAs
- ❑ Learn the optimization & implementation techniques for wideband LNA design in the domain of microwave frequencies

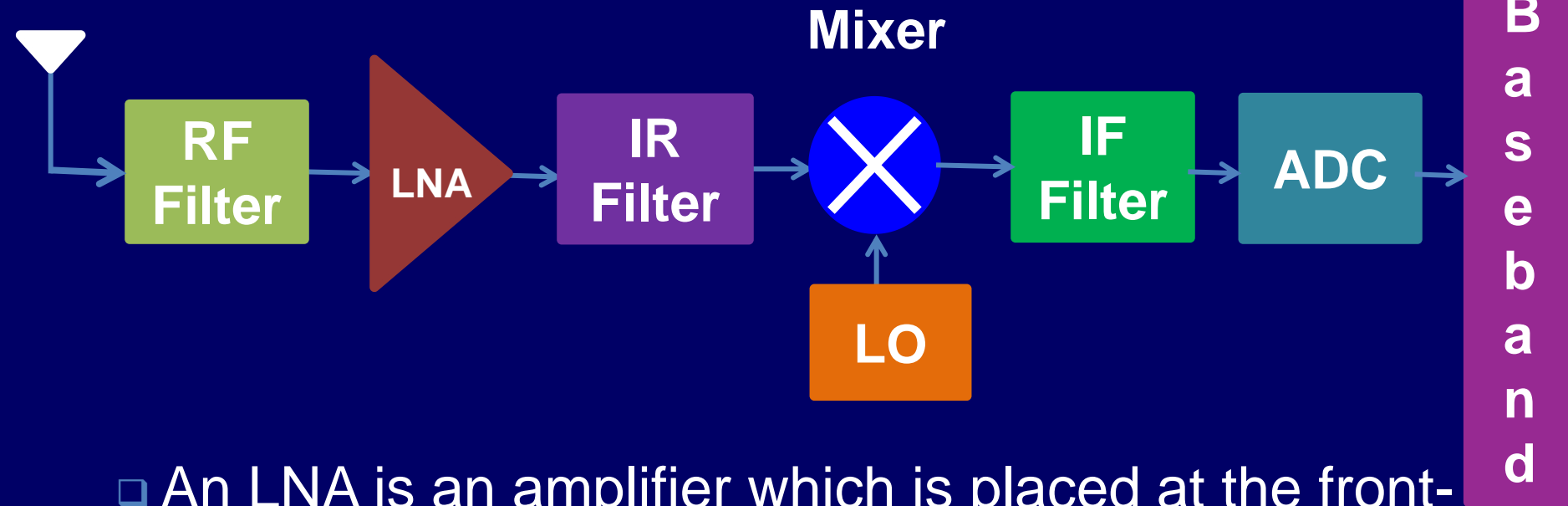


OBJECTIVES

- ❑ To develop a wideband LNA in IBM 0.13 μ m CMOS technology using Cadence software
- ❑ To have a fully integrated transmission line based design in small area
- ❑ To obtain LNA specifications better than or at least comparable to state-of-the-art LNA designs



INTRODUCTION



- ❑ An LNA is an amplifier which is placed at the front-end of an RF receiver
- ❑ Its main task is to lower the NF of the receiver. Per Friis' formula:

$$NF_{\text{total}} = NF_{\text{LNA}} + \frac{NF_{\text{other}} - 1}{G_{\text{LNA}}}$$



APPLICATIONS



- ❑ Cellular Communication
- ❑ Biomedical Telemetry
- ❑ Radio Astronomy
- ❑ Military
- ❑ Broadcast industry
- ❑ Wireless Computer Networking

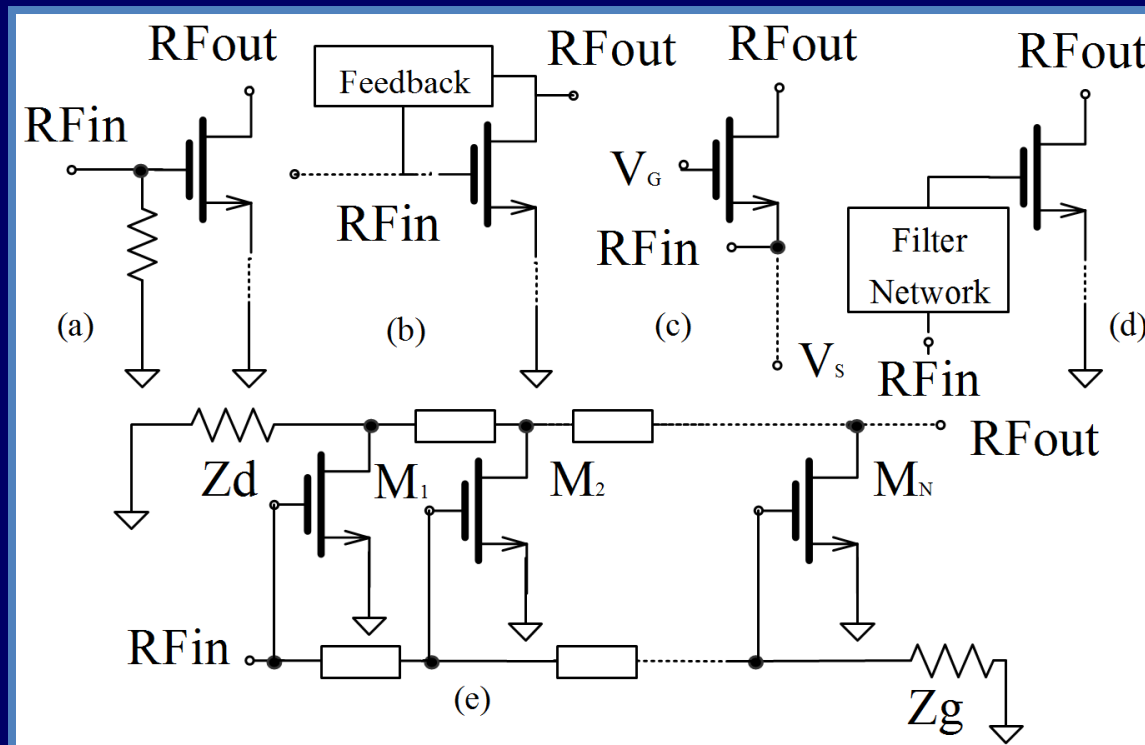




LNA SPECIFICATIONS

- Gain
 - Impedance Matching (Input and Output)
 - Noise Figure (NF)
 - Unconditional Stability
 - K (Rollet's Stability Factor)
 - Δ or B_{1f} (Alternate Stability Factor)
 - Bandwidth & Centre Frequency
 - Linearity
 - Third Order Intercept Point (IP3)
 - 1dB Compression Point (P_{1dB})
 - Power Dissipation
 - Chip Area Considerations
- S11
S12
S21
S22

COMMON WIDEBAND LNA TOPOLOGIES



(a) Common Source with resistive termination (b) Feedback
(c) Common Gate (d) Filter LNA (e) Distributed

RESISTIVE FEEDBACK TOPOLOGY



- ❑ Wideband operation because the placement of feedback resistor brings the curve of S_{11} near the central real axis of Smith chart
- ❑ Superior input matching
- ❑ Considerably flat gain throughout the bandwidth with smaller degradation of NF
- ❑ For low NF, large feedback resistor is required but it places stringent tradeoff between gain and linearity and also hampers flat gain performance

DESIGN METHODOLOGY



Step 1

- Selection of a Transistor
- DC and Transient Analyses

Step 2

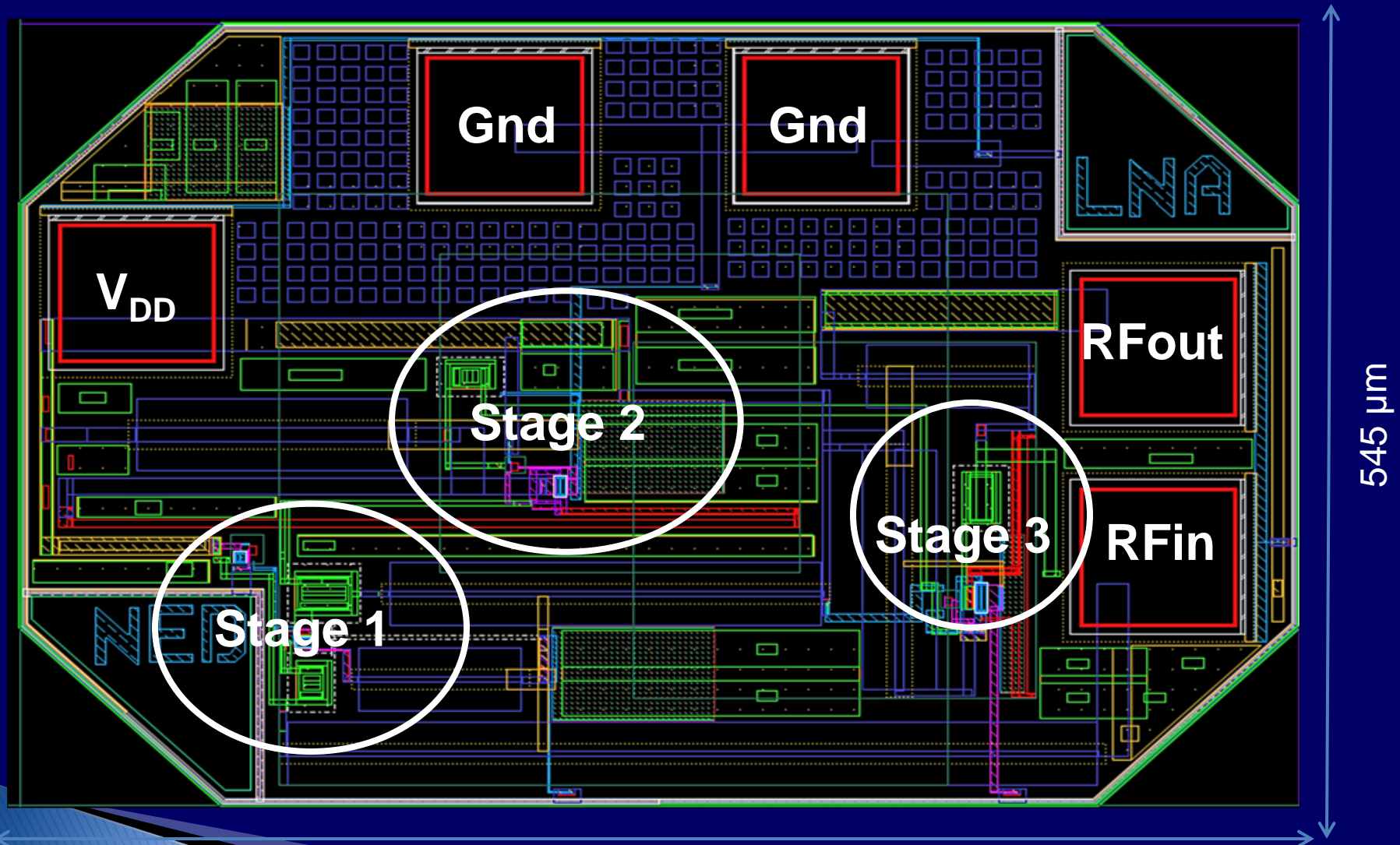
- Selection of Appropriate Configuration
- S-Parameter Analysis
- Periodic Steady State Analysis
- Optimization of the Configuration

Step 3

- Layout Design
- Physical Verification



LAYOUT DESIGN





Physical Verification

DRC (Design Rule Check)

LVS (Layout vs. Schematic)

QRC (Parasitic Extraction)

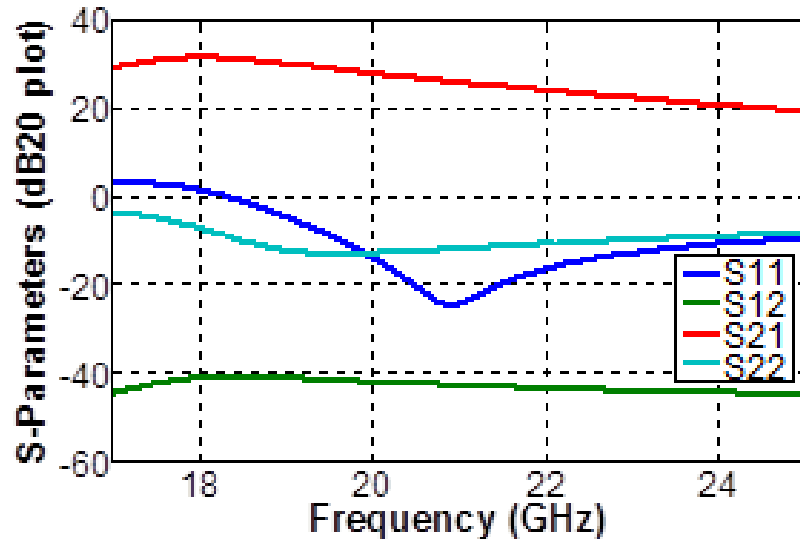
Post-Layout Simulations

Floating Gate

Local Pattern Density

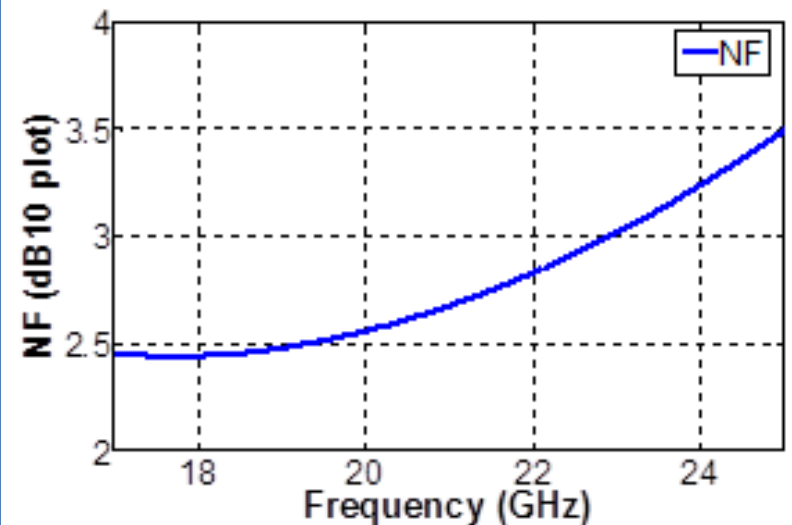
Global Pattern Density

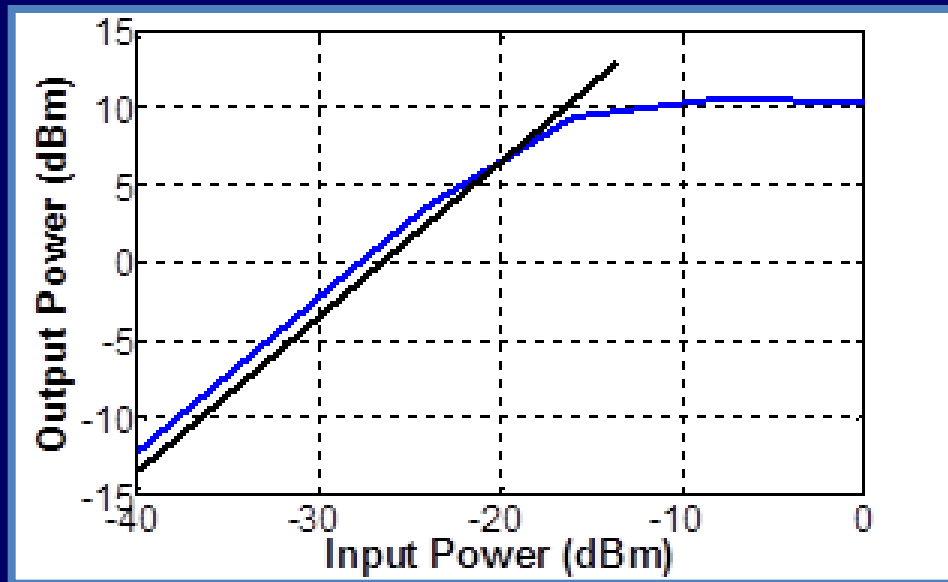
POST-LAYOUT SIMULATION RESULTS



S-Parameters

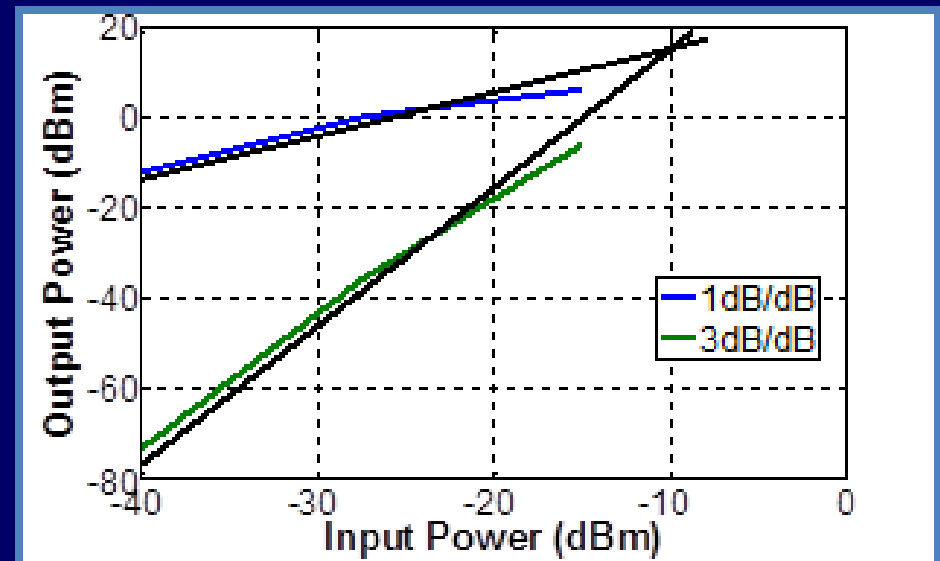
Noise Figure

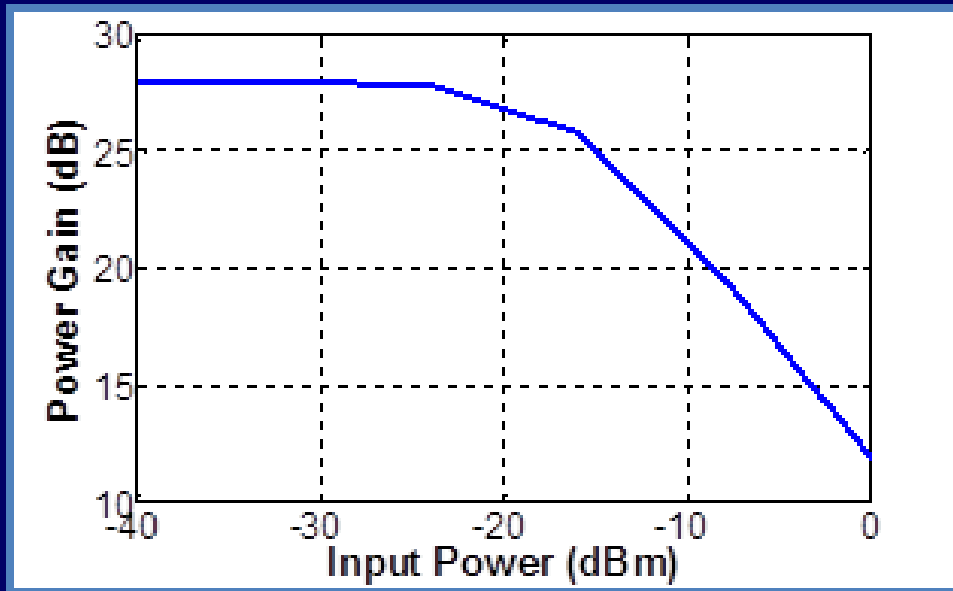




Input Referred P_{1dB} @
20GHz

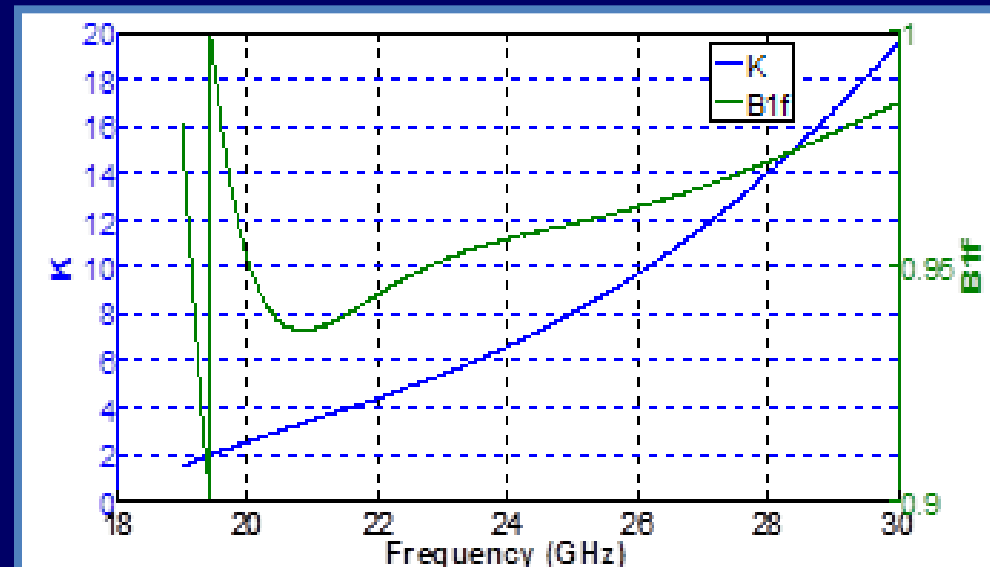
Input Referred IP3 @ 20GHz





Power Gain vs. Input Power

Stability, $K > 1$ and $B_{1f} < 1$



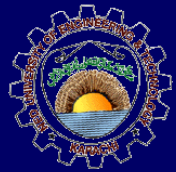


RESULTS

| | |
|----------------------------|---------------------------|
| S11 | -13dB |
| S12 | -39dB |
| S21 | 27dB |
| S22 | -12dB |
| NF | 2.55dB |
| Input referred P1dB | -21dBm |
| IIP3 | -9.5dBm |
| Power Consumption | 75mW |
| Centre Frequency | 20GHz |
| Bandwidth | 19-22GHz |
| Area* | 0.43mm² |

*including the chip edge and bond pads

COMPARISON WITH STATE-OF- THE-ART +15GHz LNAs



| Ref. | Tech μm | S_{21} dB | NF dB | Input P1dB dBm | IIP3 dBm | Power mW | Freq. GHz | Type | FOM |
|--------------------|-----------------------|----------------|-------------|----------------------|-------------|-------------|--------------|------------------------------------|-------------|
| [1] | 0.09 | 8.6 | 3 | - | 5.6 | 19.2 | 20 | Inductor (Lumped) | 10.25 |
| [1] | 0.09 | 12.9 | 2 | - | -2.3 | 19.2 | 15 | Inductor (Lumped) | 3.46 |
| [2] | 0.09 | 5.8 | 6.4 | 1 | 3 | 10 | 20 | TX Lines | 2.31 |
| [2] | 0.09 | 6 | - | -5.75 | - | 19 | 40 | TX Lines | - |
| [3] | 0.09 | 8.8 | 5.2 | - | 7 | 16.8 | 20 | Inductor (Lumped) | 7.11 |
| [4] | 0.18 | 12.9 | 5.6 | -11.1 | 2.04 | 54 | 24 | TX Lines + Inductors | 1.192 |
| [5] | 0.18 | 8.9 | 6.9 | -10.2 | 2.8 | 54 | 26 | TX Lines + Inductors | 0.6555 |
| [5] | 0.18 | 15 | 6 | - | - | 24 | 22 | Inductor (Lumped) | - |
| [6] | 0.18 | 13.1 | 3.9 | -12.2 | 0.54 | 14 | 24 | Inductor (Lumped) | 6.026 |
| [6] | 0.13 | 20 | ~5.5 | -11 | -4 | 24 | 20 | Inductor (Lumped) | 1.301 |
| [7] | 0.18 | 4 | - | - | - | 140 | 39* | Inductor-less (Distributed) | - |
| [8] | 0.18 | 8 | 3.4-5 | - | - | 34 | 0-20 | Distributed (TX Lines + Inductors) | - |
| [9] | 0.18 | 9.3 | 4.4 | -10 | 0.65 | 11.52 | 20 | Inductor (Lumped) | 3.353 |
| This Work** | 0.13 | 27 | 2.55 | -21 | -9.5 | 75 | 19-22 | TX Lines | 0.84 |

FOM=G[abs].IIP3[mW].freq[GHz]/(NF-1)[abs].Pdc[mW]

* Bandwidth

** Simulated Results Only



CONCLUSION

- ❑ A fully integrated LNA for 19-22GHz frequency band is designed in 0.13 μ m CMOS technology
- ❑ It uses cascaded common source amplifiers and resistive feedback technique to obtain wideband operation
- ❑ The post-layout simulation results are shown in graphical as well as tabular form and comparison is made with state-of-the-art +15GHz LNAs
- ❑ The design is ready for fabrication



FUTURE PROSPECTS

- ❑ The innovation, high speed requirement and compatibility with advanced digital processing systems are the major driving forces of CMOS scaling
- ❑ RFIC designers are forced to use the latest technology node for single chip integration and low cost
- ❑ Recent technology nodes do not provide precise resistors and thick layer inductors. Therefore, future LNAs must avoid inductors
- ❑ Hence, transmission lines can replace inductors to obtain wideband operation without significantly compromising the other LNA specifications such as linearity, gain, noise figure and area



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Thank You



Q & A